Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
IPC Web Site for Information on IPC-1752 Standard F				Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information											
Supplier	· Information																
Company name*			Company un	ique ID			Unique ID Aut	nority			Respons	e Date*					
onsemi											2024-04-	19					
Contact N	ame		Title - Contact				Phone - Contact*				Email - Contact*						
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorized Representative*		Title - Representative				Phone - Representative*			Email - Representative*								
Product-I	Product-Env-Stewards		Product Envi	ro Compliance	pliance NA Product-Env-Stewards@				ds@onsemi.co	m							
Requester Item Number Mfr Item		n Number	umber Mfr Item Name			Effective Date	Version	1	Manufacturing Site	acturing Site		UOM	Unit Type				
	ASX340AT2C00 D0-DRBR1			VGA 1/4 SOC		2024-04-19		,	TA1		.08.93	mg	Each				
Manufa	cturing Proccess Informa	tion															
Terminal Plating / Grid Array Material To		Terminal Base	Alloy	J-STD-020 MSI	L Rating	Peak Prod	ess Body T	Гетрегаtu	re Max Time at Peak	Temperat	ure Number	of Reflow Cyc	es				
SnAgCu		CU Alloy	lloy 3			260 C 30		30	seconds 3								
Comments																	
ATTENTI	ON: MSL 3 Rated item require	s Bake and I	Ory Pack (after	electrical test)													
For more	information regarding material	composition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	23.9	mg		Misc.	proprietary data		0.0908	mg
			Supplier	Silicon (Si)	7440-21-3		23.5726	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2366	mg
Die Attach	2.2	mg		Bismaleimide Monomer	proprietary data		0.847	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.011	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.22	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.011	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.22	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.22	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.011	mg
			Supplier	Other Additive Agents	Proprietary Data		0.44	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.22	mg
Imaging Lens	29.31	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5426	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5426	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5426	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1545	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5426	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5426	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.4426	mg
Lid Attach	1.52	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.38	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.102	mg
			Supplier	Misc.	Proprietary Data		0.038	mg
Mold Compound	8.1	mg		Epoxy resin	proprietary data		2.0088	mg
			Supplier	Other Additive Agents	Proprietary Data		0.2592	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.81	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.779	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.243	mg
Solder Ball	24.55	mg	Supplier	Silver (Ag)	7440-22-4		0.7365	mg

			Supplier	Tin (Sn)	7440-31-5	23.6907	mg
			Supplier	Copper (Cu)	7440-50-8	0.1227	mg
Solder Mask	2.06	mg		Epoxy resin	proprietary data	0.2472	mg
			Supplier	Acrylate	Proprietary Data	0.7869	mg
			Supplier	Talc	14807-96-6	0.0556	mg
			Supplier	Miscellaneous	Trade Secret	0.0762	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.894	mg
Substrate Copper Foil	1.59	mg	Supplier	Copper (Cu)	7440-50-8	1.59	mg
Substrate - Core Material	7.88	mg		Epoxy resin	proprietary data	1.7076	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	6.1724	mg
Substrate Plating-Au	0.14	mg	Supplier	Gold (Au)	7440-57-5	0.14	mg
Substrate Plating-Cu	7.1	mg	Supplier	Copper (Cu)	7440-50-8	7.1	mg
Substrate Plating-Ni	0.33	mg	В	Nickel (Ni)	7440-02-0	0.33	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5	0.25	mg